

# CONSOLIDATED VERSION



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**Environmental testing –  
Part 2-58: Tests – Test Td: Test methods for solderability, resistance to  
dissolution of metallization and to soldering heat of surface mounting devices  
(SMD)**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### ENVIRONMENTAL TESTING –

#### **Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)**

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